PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5292459

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
DENZIL S. FROST	11/28/2018
RICHARD T. HOUSLEY	11/27/2018
JIANMING ZHOU	12/08/2018

RECEIVING PARTY DATA

Name:	MICRON TECHNOLOGY, INC.
Street Address:	8000 SOUTH FEDERAL WAY, MS 1- 525
City:	BOISE
State/Country:	IDAHO
Postal Code:	83716

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16226074

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	BRIDGET WISEMAN
SIGNATURE:	/Bridget Wiseman/
DATE SIGNED:	12/19/2018

Total Attachments: 6
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ASSIGNMENT

PARTIES TO THE ASSIGNMENT:

INVENTORS:

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United States

Richard T. Housley
2431 N. Bruins Circle
Boise, ID 83704
United States

Jianming Zhou
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China

ASSIGNEE:

Micron Technology, Inc.
MS 1-525
8000 South Federal Way
Boise, ID 83716
United States

BACKGROUND OF THIS ASSIGNMENT:

Inventors have conceived certain new and useful inventions disclosed in a United States patent application titled "An Integrated-Circuitry Overlay Alignment Mark, A Substrate Comprising An Overlay Alignment Mark, A Method Of Forming An Overlay Alignment Mark In The Fabrication Of Integrated Circuitry, And A Method Of Determining Overlay Alignment In The Fabrication Of Integrated Circuitry".

Micron Technology, Inc. (hereinafter referred to as "ASSIGNEE") desires to acquire the entire right, title and interest in said inventions and with respect to any Letters Patent(s) that may be granted with respect to the inventions in both the United States and in all foreign countries.

THE PARTIES AGREE AS FOLLOWS:

In consideration of good and valuable consideration, the receipt, sufficiency and adequacy of which is hereby acknowledged, INVENTORS have sold, assigned and transferred, and by these present do hereby sell, assign and transfer to ASSIGNEE the entire right, title and interest in the above-identified inventions and patent application(s) and to any reissues, renewals, divisions or continuations of the application(s) thereof, and hereby authorizes the Commissioner of Patents and Trademarks to issue such Letters Patent(s) to ASSIGNEE for the sole use of ASSIGNEE, its successors or assigns.

INVENTORS further agree to execute, at the request and expense of ASSIGNEE, such other formal documents as may be required to fully convey the interest transferred herein and will similarly execute any patent application papers (foreign or domestic) required for the filing of any divisional, continuation, renewal or reissue of the patent application(s) or resulting Letters Patent(s); and will generally do everything necessary or desirable to obtain and enforce proper protection for the inventions assigned hereby.

INVENTORS further assign to ASSIGNEE the whole right, title and interest in the inventions disclosed in the application(s) throughout all countries foreign to the United States. ASSIGNEE is hereby authorized to apply for patents relating to the inventions in its own name in countries where such procedure is proper; to claim the benefit of the International Convention; to file and prosecute International Applications relating to the inventions under the Patent Cooperation Treaty; and to file and prosecute applications relating to the inventions under the European Patent Convention. INVENTORS agree to execute application(s) relating to the inventions in those countries and under those conventions where it is necessary that the same be executed by the inventor, and to execute assignments of such applications and the resulting Letters Patent(s) to ASSIGNEE as well as all other necessary papers in relation to such applications and Letters Patent(s). INVENTORS hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country as proof of the right of ASSIGNEE to apply for patent and other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

To be binding on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

Dated: 11/28/17 Signature:
Denzil S. Frost

Dated: 11-27-18

Signature: Richard T. Housley
Richard T. Housley

Dated: Dec/8/2018 Signature: ______________________
Jianming Zhou

On this day before me personally appeared Jianming Zhou, known or identified to me (or proved to me on the basis of satisfactory evidence) to be the person whose name is subscribed within the Assignment, and acknowledged to me that he/she executed the Assignment in his/her authorized capacity, and that by his/her signature on the Assignment, the person executed the Assignment.

Witness Name (printed): 吕永奎
Witness Signature: ______________________
Date: 2018. 12. 8

Witness Name (printed): 陈好
Witness Signature: 陈好
Date: 2018. 12. 8